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2SB561

Silicon PNP Epitaxial

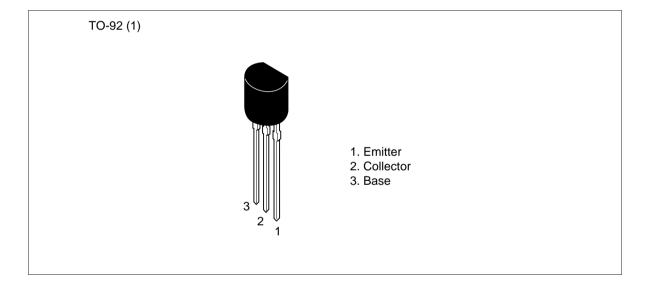


ADE-208-1023 (Z) 1st. Edition Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SD467

Outline



2SB561

Absolute Maximum Ratings (Ta = 25°C)

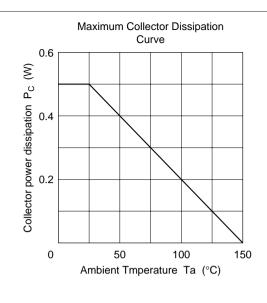
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	– 25	V
Collector to emitter voltage	V_{CEO}	-20	V
Emitter to base voltage	V_{EBO}	- 5	V
Collector current	I _c	-0.7	A
Collector peak current	i _{C(peak)}	-1.0	А
Collector power dissipation	P _c	0.5	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

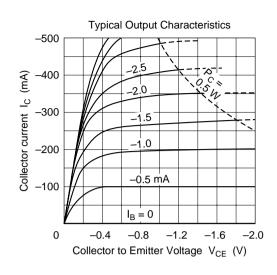
Electrical Characteristics ($Ta = 25^{\circ}C$)

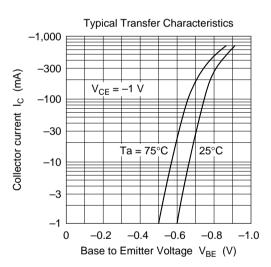
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-25	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-20	_	_	V	$I_{C} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{\text{(BR)EBO}}$	- 5	_	_	V	$I_{E} = -10 \ \mu\text{A}, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	-1.0	μΑ	$V_{CB} = -20 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE} *1	85	_	240		$V_{CE} = -1 \text{ V},$ $I_{C} = -0.15 \text{ A (Pulse test)}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})}$	_	-0.2	-0.5	V	$I_{\rm C} = -0.5 \text{ A}, I_{\rm B} = -0.05 \text{ A}$
Base to emitter voltage	V _{BE}	_	-0.75	-1.0	V	$V_{CE} = -1 \text{ V}, I_{C} = -0.15 \text{ A}$
Gain bandwidth product	$f_{\scriptscriptstyle T}$	_	350	_	MHz	$V_{CE} = -1 \text{ V}, I_{C} = -0.15 \text{ A}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0$ f = 1 MHz

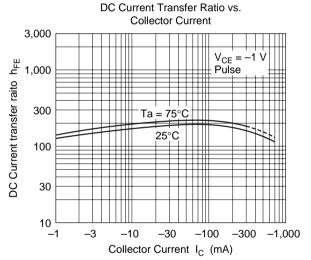
Note: 1. The 2SB561 is grouped by h_{FE} as follows.

В	С
85 to 170	120 to 240



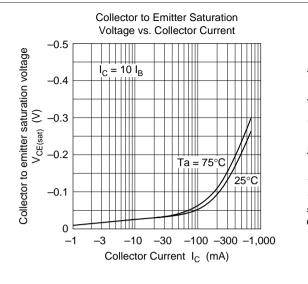


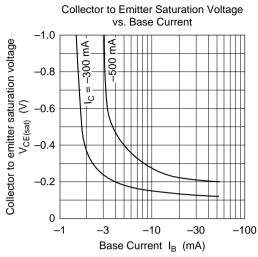


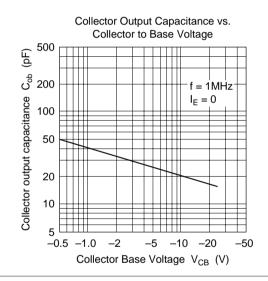


3

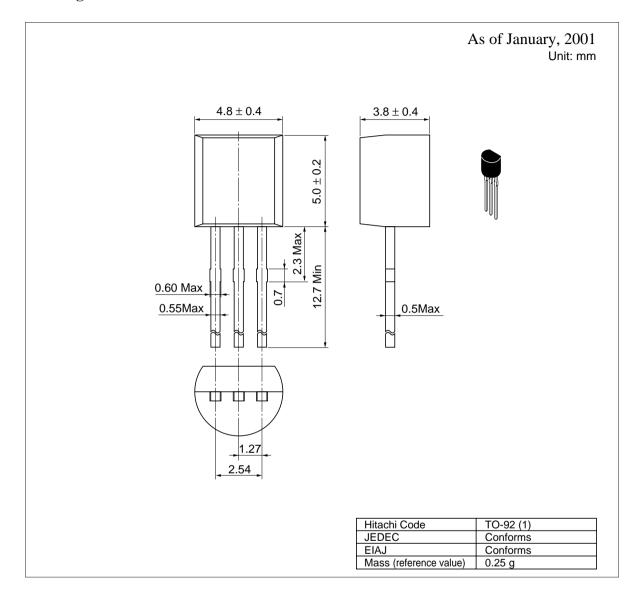
2SB561







Package Dimensions



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